

ABSTRACT

Providing a method for manufacturing a multilayer wiring board and a touch panel, which does not cause decreasing of yields, reliabilities and productivities even though the materials of each board to be stacked are different, and which manufactures the multilayer wiring board and the touch panel at low cost with high productivities. A multilayer wired board constituting at least part of a electrical circuit board in which a plurality of wired boards are stacked so as to face their wired surfaces each other, wherein: electrical connection parts between the multilayer wired boards are connected through an elastic conductive material part adhered to one of the wired boards; and at least part of a peripheral edge portion of the elastic conductive material part is adhered by a double-sided adhesive material part to seal the plurality of multilayer wired boards.